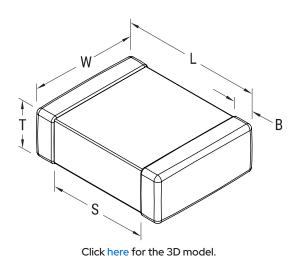




ESD SMD Comm COG, Ceramic, 1,500 pF, 5%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0402, 0.3 mm



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.06 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
S	0.3mm MIN
В	0.3mm +/-0.1mm

Packaging Specifications	
В	0.3mm +/-0.1mm
S	0.3mm MIN
Т	0.5mm +/-0.05mm
VV	0.5mm +/-0.05mm

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

Specifications	
Capacitance	1,500 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	25 VDC
ESD Level per AEC-Q200	6,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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